# ROYALOHM

#### SPECIFICATION FOR APPROVAL

#### TRELIK COMERCIAL IMPORTADORA LTD.

Description: Thick Film Chip Resistors (Terminal Lead Free)

#### Royalohm Part no.:

0805W8xxxxxT5E (RMC 1/8W (0805) +/-1%, 5% & Jumper T/R-5K)

Approved by					

Parts corresponding to RoHS Compliant: 2005-Apr.-1

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Approved	Checked	Prepared
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Issue Date: 2009/08/18

	CHANGE NOTIFICATION HISTORY							
Version	Date of Version	History	Remark					
1	2009/08/18	Chip series (0805) @ 1/8W						
		Resistance tolerance: ±1%, ±5% & Jumper						
		Temperature coefficient : $1\Omega$ - $10\Omega$ : $\pm 400$ PPM/°C						
		$11\Omega$ -100Ω: ±200 PPM/°C						
		$>100\Omega$ : $\pm 100 \text{ PPM/}^{\circ}\text{C}$						
		+						
		+						

#### 1. Scope:

This specification for approval relates to Thick Film Chip Resistors (Terminal Lead Free) manufactured by ROYALOHM 's specifications.

#### 2. Type designation:

The type designation shall be in the following form:

Ex.

Type	Power Rating	Resistance tolerance	Nominal Resistance
RMC 0805	0.125W (1/8W)	F, J	1ΚΩ

#### 3. Ratings:

Туре	RMC 0805
Power Rating	0.125W (1/8W)
Rated Current (Jumper)	2A
Max. Overload Current (Jumper	5A
Max. Working Voltage	150 V
Max. Overload Voltage	300 V
Temperature Range	-55°C ∼ +155°C
Ambient Temperature	70 ℃

#### 3.1 Power rating:

Resistors shall have a power rating based on continuous load operation at an ambient temperature of 70  $^{\circ}$ C . For temperature in excess of 70  $^{\circ}$ C , The load shall be derate as shown in figure 1.

Figure 1

Figure 1

-55°C +170°C +155°C

00

80

60

40

20

-60 -40 -20 0 20 40 60 80 100 120 140 160 1

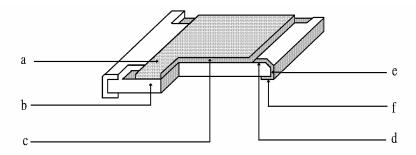
3.2 Nominal Resistance

Effective figures of nominal resistance shall be in accordance with E-24 and E-96 series. E-96 series for 1% and E-24 series for 2%, 5%.

Ambient temperature (°C)

# **Thick Film Chip Resistors (Terminal Lead Free)**

#### 4. Construction:



a. Protective coating: Epoxy

b. Al<sub>2</sub> O<sub>3</sub> high purity alumina substrate : Al 96 %

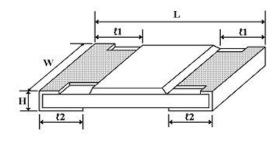
c. Resistive element :  $RuO_2$ , Ag, Glass

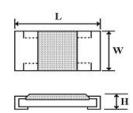
d. Termination (Inner ): Ag/Pd

e. Termination (Between): Ni plating film

f. Termination (Outer): Sn plating film

### 5. Power rating and dimensions





#### Dimension:

	Dimension (mm)						
Туре	$L \pm 0.15$	W + 0.15 - 0.10	$H \pm 0.10$	$\ell 1 \pm 0.20$	$\ell 2 \pm 0.20$		
RMC 0805	2.00	1.25	0.55	0.40	0.40		

## Power Rating:

Туре	Power Rating	Tolerance	Resistance	Standard
-71	at 70 ℃	%	Range	Series
	0.12511	Jumper	$< 50 \text{m}\Omega$	
RMC 0805	0.125W (1/8W)	± 1	$1\Omega\sim 1M\Omega$	E-96
	(1/3W)	± 5	$1\Omega \sim 10 M\Omega$	E-24

	T	hick Film (	Chip R	lesisto	rs (Termina	l Lead Free)
6. Marking :						
6.1 Resis	stors					
A. Mai	rking for	E-96 series in (	)805 size	: 4 Dig	its	
*The f	irst 3 dig	its are singnific	ant figur	es of res	sistance and the	4th digit denoted number of zeros.
Ex.		1003		100	$K\Omega$	
*For o	hmic valı	ues below 100 g	2, letter"	R" is fo	r decimal point.	
		1000			_	
Ex.		1R80		1.89	2	
D. Mor	dring for	E 24 garing in C	1905 aiga	」 ∴2 Dia	ita	
	-	E-24 series in 0		_		3rd digit denoted number of zeros.
THE	nst 2 dig	its are singiline	ant figur		sistance and the s	ord digit denoted number of zeros.
Ex.		102		1K 9	$\Omega$	
*For o	hmic valı	ues below 10 Ω	, letter"F	" is for	decimal point.	
Ex.		R68		0.68	$S\Omega$	
6.2 Labe	ls					
Label s	shall be n	narked with the	followin	ng item		
A. No	minal Re	sistance and Re	esistance	Tolerar	nce	
B. Pov	wer Ratin	ig and Size				
C. Qu						
D. Par						
E. P.C						
F. Lot	No.		DOV	A I OIII	Δ.//	
Ex.		(	KOY <i>E</i> CHIP R	ALOHI		
	•	RESISTANCE:	1K	Ω	± 5%	
		WATTAGE:	1/8W		SIZE: 0805	
		QUANTITY:	5,000	PCS	Pb-Free	
		PART NO.:				
		P.O.NO.:				
		LOT NO.: 605	8000	0805W	/8J0102T5E	
						<b> </b>

**Remark:** Label is 1K, value is  $1K\Omega$ , marking is 102

	Thick Film Chip Resist	ors (Terminal Lead Free)
7. Performance sp	pecification :	
Characteristics	Limits	Test Methods ( JIS C 5201-1 )
*Insulation resistance	$1,000~\mathrm{M}\Omega$ or more	Apply 500V DC between protective coating and termination for 1 min, then measure (Sub-clause 4.6)
*Dielectric withstanding voltage	No evidence of flashover mechanical damage, arcing or insulation break down	Apply 500V AC between protective coating and termination for 1 minute (Sub-clause 4.7)
Temperature coefficient	$1\Omega$ -10Ω: ± 400 PPM/°C $11\Omega$ -100Ω: ± 200 PPM/°C >100Ω: ± 100 PPM/°C	Natural resistance change per temp.  degree centigrade.  R2-R1  x 10 <sup>6</sup> (PPM/°C)  R1(t2-t1)  R1: Resistance value at room temperature (t1)  R2: Resistance value at room temp. plus 100 °C (t2)  (Sub-clause 4.8)
Short time overload	Resistance change rate is $\pm 5\% (2.0\% + 0.1 \Omega)$ Max. $\pm 1\% (1.0\% + 0.1 \Omega)$ Max.	Permanent resistance change after the application of a potential of 2.5 times RCWV for 5 seconds (Sub-clause 4.13)
*Solderability	95 % coverage Min.	Test temperature of solder : 245 ± 3°C  Dipping them solder : 2-3 seconds  (Sub-clause 4.17)
Soldering temp. reference	Electrical characteristics shall be satisfied. Without distinct deformation in appearance. (95 % coverage Min.)	Wave soldering condition: (2 cycles Max.)  Pre-heat: 100 ~ 120 °C, 30 ± 5 sec.  Suggestion solder temp.: 235 ~ 255 °C, 10 sec. (Max.)  Peak temp.: 260 °C  Reflow soldering condition: (2 cycles Max.)  Pre-heat: 150 ~ 180 °C, 90 ~ 120 sec.  Suggestion solder temp.: 235 ~ 255 °C, 20 ~ 40 sec.  Peak temp.: 260 °C  Peak: 260 °
		Hand soldering condition:  The soldering iron tip temperature should be less than 300°C and maximum contract time should be 5 sec.

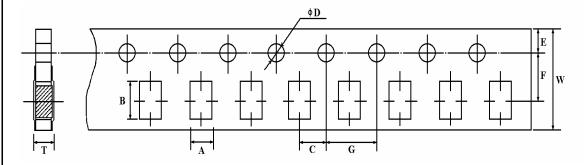
	Thick Film Chip Resi	stors (Term	inal Lead Free)			
7. Performance sp	pecification:					
Characteristics	Limits	Test Methods ( JIS C 5201-1 )				
Soldering Heat	Resistance change rate is: $\pm (1\% + 0.05\Omega)$ Max.	Dip the resistor into a solder bath having a temperature of 260°C±3°C and hold it for 10±1 seconds.  (Sub-clause 4.18)				
			nange after continuous duty cycle specified be			
	Resistance change rate is	Step	Temperature	Time		
Temperature	$\pm 5\% (1.0\% + 0.05 \Omega)$ Max.	1	-55°C ± 3°C	30 mins		
cycling	$\pm 1\% (0.5\% + 0.05 \Omega)$ Max.	2	Room temp.	10~15 mins		
		3	+155°C ± 2°C	30 mins		
		4	Room temp.	10~15 mins		
		(Sub-clause 4	4.19)			
		Resistance ch	nange after 1,000 hour	rs .		
Load life in	Resistance change rate is	(1.5 hours "o	n", 0.5 hour "off" ) at	RCWV		
humidity	$\pm 5\% (3.0\% + 0.1 \Omega)$ Max.	in a humidity	chamber controlled a	t		
	$\pm 1\% (1.0\% + 0.1 \Omega)$ Max.	40°C ± 2°C a	nd 90 to 95 % relative	humidity		
		(Sub-clause 4	1.24.2.1)			
	Resistance change rate is	Permanent re	esistance change after	1,000 hours		
Load Life	$\pm 5\% (3.0\% + 0.1 \Omega)$ Max.	operating at I	RCWV, with duty cyc	le of		
	$\pm 1\% (1.0\% + 0.1 \Omega)$ Max.	(1.5 hours"or	n", 0.5 hour"off") at 70	$0^{\circ}$ C ± $2^{\circ}$ C ambient		
		(Sub-clause 4.25.1)				
Terminal	Resistance change rate is	Twist of Test	t Board :			
bending	$\pm (1.0\% + 0.05 \Omega)$ Max.	Y/X = 5/90  n	nm for 10 seconds			
		(Sub-clause 4	1.33)			

The resistors of  $0\Omega$  only can do the characteristic noted of \*

# Thick Film Chip Resistors (Terminal Lead Free)

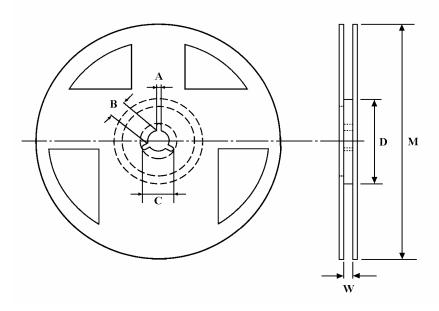
# 8. Packing specification:

\* Taping Dimension (mm)



Туре	A ± 0.2	B ± 0.2	$C \pm 0.05$	φ D +0.1 - 0	E ± 0.1	$F \pm 0.05$	$G \pm 0.1$	W ± 0.2	T ± 0.1
RMC 0805	1.65	2.4	2.0	1.5	1.75	3.5	4.0	8.0	0.81

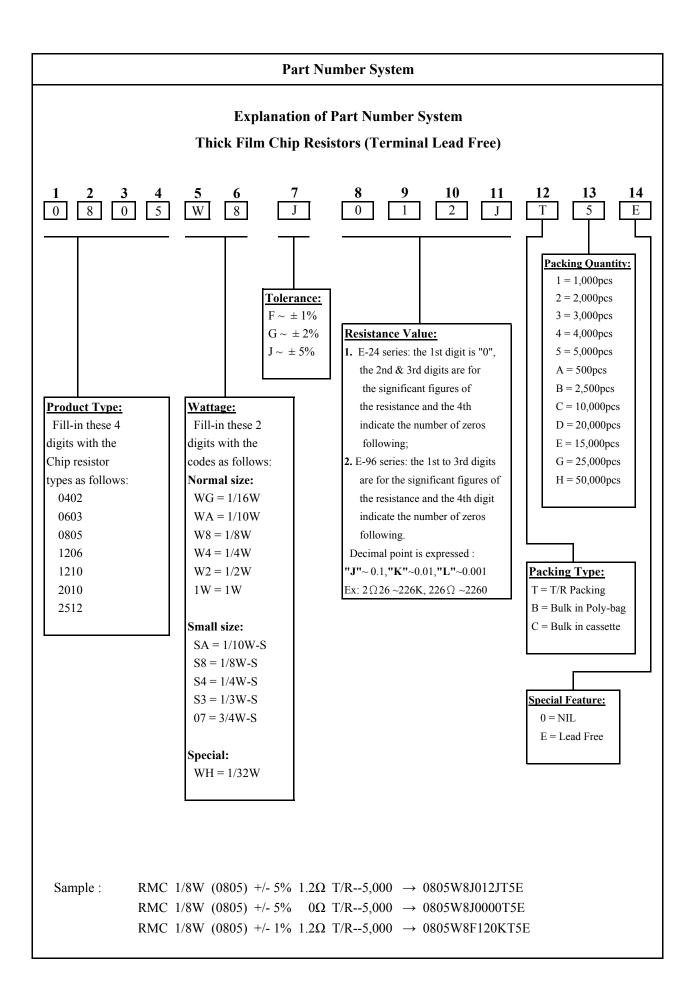
\* Reel Dimension (mm)



Туре	Quantity Per Reel	$A \pm 0.5$	$B \pm 0.5$	$C \pm 0.5$	D ± 1	$M \pm 2$	W ± 1
RMC 0805	5,000 pcs./ Reel	2	13	21	60	178	10

Remark :  $\phi M 10,000 pcs. / Reel = 255 \pm 2mm$ 

20,000pcs. / Reel =  $330 \pm 2$ mm



## Thick Film Chip Resistors (Terminal Lead Free)

#### **Environment Related Substance**

This product complies to EU RoHS directive, EU PAHs directive, EU PFOS directive and Halogen free.

Ozone layer depleting substances.

Ozone depleting substances are not used in our manufacturing process of this product.

This product is not manufactured using Chloro fluorocarbons (CFCs), Hydrochlorofluorocarbons (HCFCs),

Hydrobromofluorocarbons (HBFCs) or other ozone depleting substances in any phase of the manufacturing process.

#### **Storage Condition**

The performance of these products, including the solderability, is guaranteed for a year from the date of arrival at your company, provided that they remain packed as they were when delivered and stored at a temperature of  $25^{\circ}\text{C} \pm 5^{\circ}\text{C}$  and a relative humidity of  $60\%\text{RH} \pm 10\%\text{RH}$ 

Even within the above guarantee periods, do not store these products in the following conditions. Otherwise, their electrical performance and/or solderability may be deteriorated, and the packaging materials (e.g. taping materials) may be deformed or deteriorated, resulting in mounting failures.

- 1. In salty air or in air with a high concentration of corrosive gas, such as Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, or NO<sub>2</sub>
- 2. In direct sunlight